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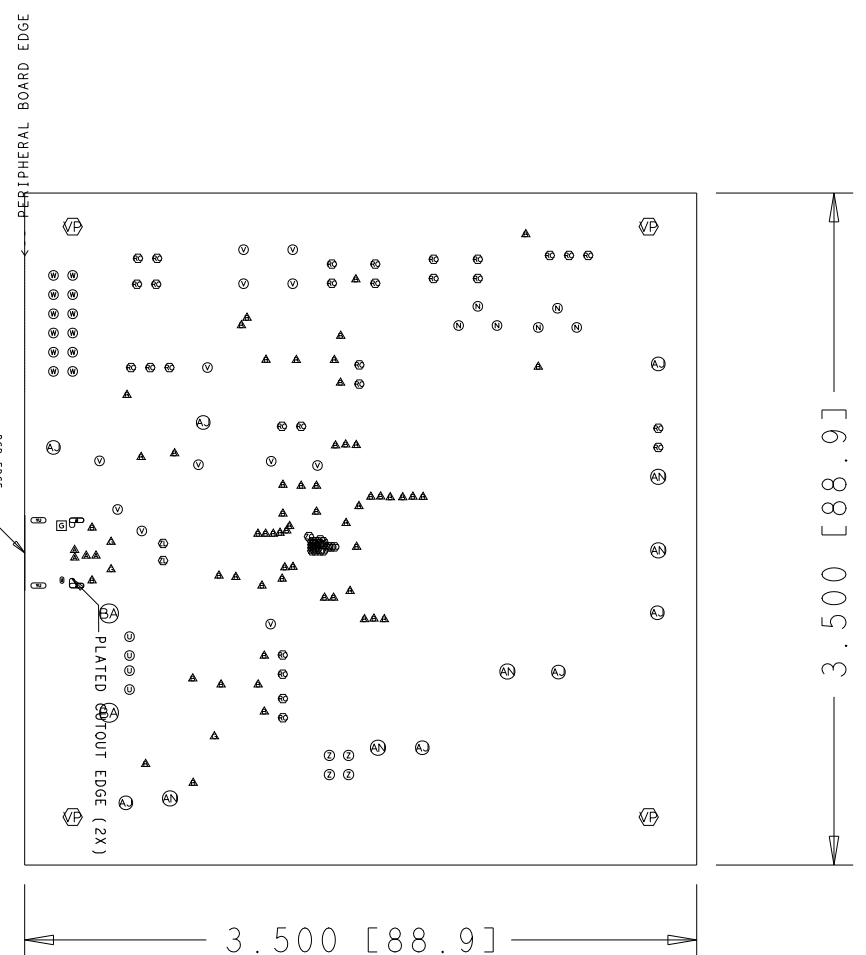
IMPEDANCE TABLE				
LAYER	50 OHM	65 OHM	80 OHM TRACE / SPACE	75 OHM TRACE / SPACE
TOP	-	-	0.00800/0.00800	-

NOTE: DO NOT EDIT THIS TABLE MANUALLY USE IMPEDANCE TABLE GENERATOR FROM MAXIMTOOLS.

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	COPPER THICKNESS (OZ./INCH)	DIELECTRIC THICKNESS (IN.)	DIELECTRIC MATERIAL
1	TOP	1.0Z 0.0014" MIN		FOIL
2	L02_GND	0.5 OZ 0.007"	T80	ISOLA 370HR/EQUIVALENT
3	L03_SIGS	0.5 OZ 0.007"	T80	ISOLA 370HR/EQUIVALENT
4	BOTTOM	1.0Z 0.0014" MIN		FOIL

THE FINISHED PCB THICKNESS TO BE: 0.0625" +/-0.010"

DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	QTY	NOTES
⊕	4.0	+0.0/-4.0	PLATED	18	
⊕	6.0	+3.0/-4.0	PLATED	4	
⊕	8.0	+3.0/-6.0	PLATED	57	
⊕	12.0079	+3.0/-3.0	PLATED	2	
⊕	20.0	+3.0/-18.0	PLATED	3	
⊕	27.56	+3.0/-3.0	PLATED	6	
⊕	36.0	+3.0/-3.0	PLATED	28	
⊕	37.4	+3.0/-3.0	PLATED	4	
⊕	39.37	+3.0/-3.0	PLATED	12	
⊕	41.3386	+3.0/-3.0	PLATED	12	
⊕	45.28	+3.0/-3.0	PLATED	4	
⊕	62.9921	+3.0/-3.0	PLATED	7	
⊕	70.8661	+3.0/-3.0	PLATED	5	
⊕	90.55	+3.0/-3.0	PLATED	2	
⊕	125.0	+3.0/-3.0	PLATED	4	
⊕	23.62	+3.0/-3.0	NON-PLATED	1	
⊕	74.8x23.62	+3.0/-3.0	PLATED	2	
⊕	78.74x27.56	+3.0/-3.0	PLATED	2	
⊕	33.46x19.69	+3.0/-3.0	NON-PLATED	1	



TOLERANCES UNLESS OTHERWISE SPECIFIED			THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.		
FRACTIONS	DECIMALS	ANGLES			
+/-	.XX +/- .01 .XXX +/- .005	+/-	DRAWN BY: NN DATE: 07/18/17		
MATERIAL:	SEE NOTES		CHECKED BY: DATE:		
FINISH:	SEE NOTES		APPR. BY: B.M DATE: 07/18/17		
			APPR. BY: DATE:		
			NOT TO SCALE		
			SHEET 1 OF 1		

- NOTES:
- UNLESS OTHERWISE SPECIFIED
 - DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
 - MATERIAL: (USE CHECKED ITEMS FOR MATERIAL)
 - BOARD MATERIAL:
 - (X) ISOLA 370HR OR EQUIVALENT
 - () ISOLA-FR408HR OR EQUIVALENT
 - () NELCO-4000-13
 - () MEGTRON 6
 - () ROGERS 4350B
 - () ROGERS 4003C
 - () OTHER -----
 - THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
 - BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796 WITH FLAMMABILITY RATINGS OF 94V-0.
 - OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
 - BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.75%) PER LINEAR INCH. BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
- TOOLING: (USE CHECKED ITEMS FOR TOOLING)
- PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER R5274X OR ODB++ FORMAT FILE. DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CNC DRILL FILE.
 - IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE SHALL BE DETERMINED BY THESE LAYERS HAVING A CHARACTERISTIC IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.
 - ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:
 - () FILLETED
 - (X) NOT FILLETED
 - LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES. LEGEND TO LEGEND +/- 0.007 INCHES
- FINISH: (USE CHECKED ITEMS FOR PLATING)
- PLATING SPECIFICATION:
 - () STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ). THE FINISH COPPER WEIGHT IS (1 OZ). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (1 OZ) UNLESS OTHERWISE SPECIFIED
 - () STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ). THE FINISH COPPER WEIGHT IS (2 OZ). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ). UNLESS OTHERWISE SPECIFIED
 - () STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2 OZ). THE FINISH COPPER WEIGHT IS (2 OZ) MINIMUM. FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2 OZ) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (<2 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ). UNLESS OTHERWISE SPECIFIED
 - () OTHER -----
 - CHECK ALL THAT APPLY
 - () ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C (KNOPF HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C. GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0, CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-600 MICROINCHES THICK).
 - () FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
 - () FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER 118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
 - () FINGERS TO BE GOLD PLATED.
 - () LEAD FREE AND RoHS COMPLIANT PLATING.
 - () OTHER -----
 - DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 BTP MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING.
 - CHECK ALL THAT APPLY
 - () GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI) PER ARTWORK.
 - () GREEN TAIYO PSR-4000
 - () OTHER -----
 - CHECK ALL THAT APPLY
 - (X) APPLY SILKSCREEN USING A NON-CONDUCTIVE, WHITE EPOXY BASED INK PER ARTWORK.
 - () OTHER -----
 - VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYWW ONLY TESTING:
 - FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE. (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE) THE PCB SHALL HAVE A VERIFICATION STAMP.
 - A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TOR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE, ALL OTHER INSTANCES MUST BE REPORTED.
- MISCELLANEOUS:
- IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY. UNLESS OTHERWISE SPECIFIED.
 - FOR ALL DRILL INFORMATION REFER TO DRILL CHART:
 - (X) NON-CONDUCTIVE EPOXY, FILL AND CAP ALL 0.004 INCH DRILLED VIAS.
 - () SILVER, FILL AND CAP ALL 0.004 INCH DRILLED VIAS.
 - FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES, PROBE MARKS OR OTHER DEFORMITIES THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.
 - THEFTING:
 - () SUPPLIER MAY ADD THEFTING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
 - (X) SUPPLIER MAY NOT ADD THEFTING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
 - PEMNUIT
 - () PEMNUTS TO BE INSTALLED BY SUPPLIER
 - () PEMNUTS NOT TO BE INSTALLED BY SUPPLIER
 - (X) NOT APPLICABLE

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